



ITEQ Corporation

2025 Second Quarter Investor Presentation

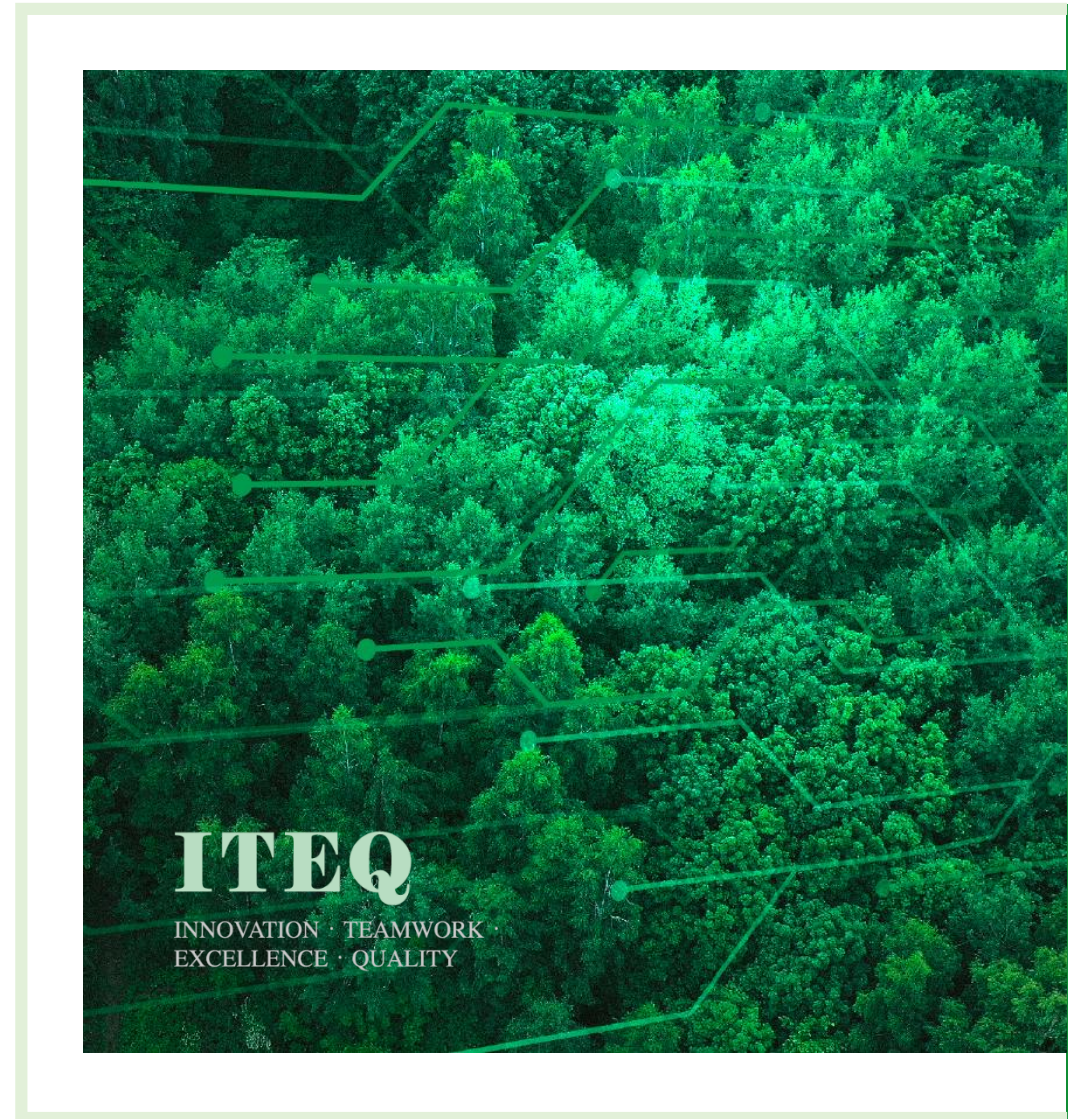
ITEQ

INNOVATION. TEAMWORK. EXCELLENCE. QUALITY

Aug 2025

Disclaimer Statement

- This presentation and release contain “forward-looking statements” which may include projections of future results of operations, financial condition or business prospects based on our own information and other sources.
- Our actual results of operations, financial condition or business prospects may differ from those expressed or implied in these forward-looking statements for a variety of reasons, including but not limited to market demand, price fluctuations, competition, international economic conditions, supply chain issues, exchange rate fluctuations and other risks and factors beyond our control.
- The forward-looking statements in this release reflect the current belief of ITEQ as of the date of this release. ITEQ undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.



Company Overview



Establishment
April 10th, 1997



Headquarters
HsinChu, Taiwan



Capital
NT\$3,630 million



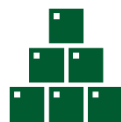
Employees
~4,000



Chairman
Dennis Chen



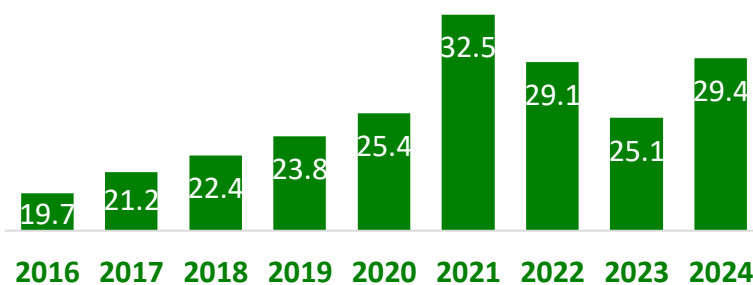
CEO
Audrey Tsai



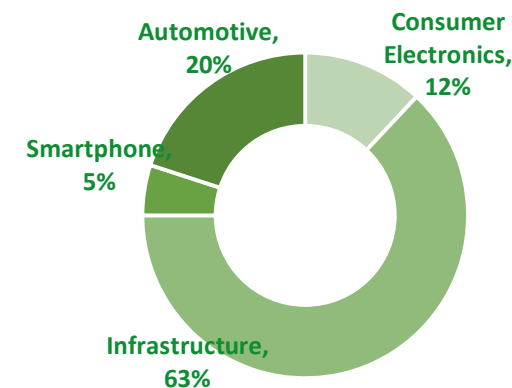
Main Products

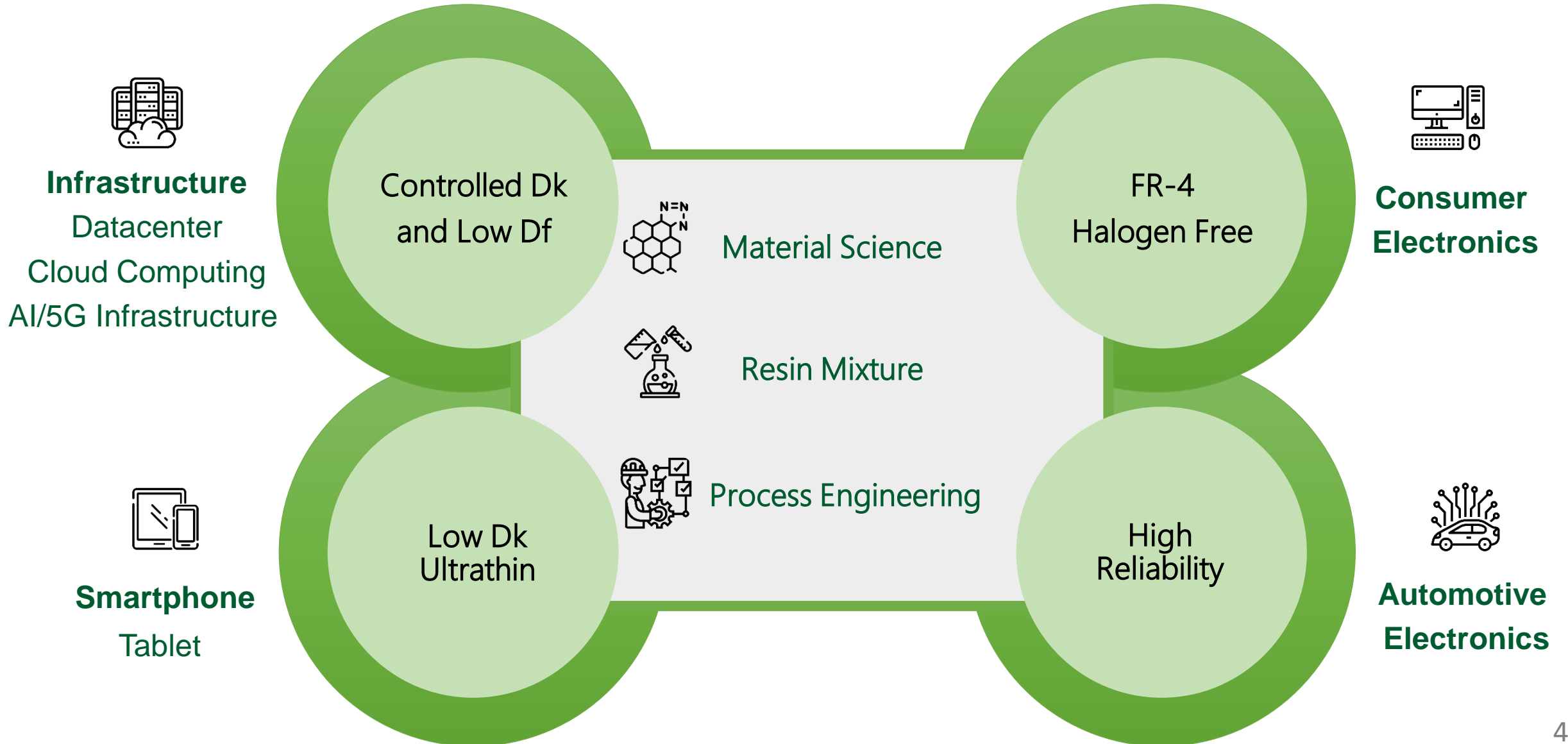
Copper Clad Laminate (CCL) & Prepreg (PP) | Masslam service | Flexible CCL

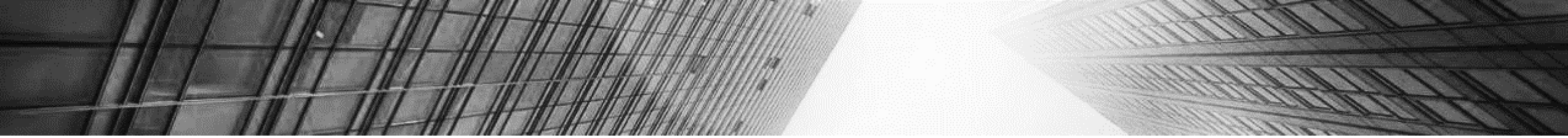
Revenue (NT\$ billion)



Revenue by Application (FY24)







Growth Strategy Blueprint

ITEQ

ITEQ

INNOVATION • TEAMWORK •
EXCELLENCE • QUALITY

Path of Innovation

Widely adopted in consumer electronics



Engaged with tier 1 automotive players



Enhanced ultra-thin dielectric capability for handheld devices



Biz kick-off with top server OEMs & ODMs



Dominant CCL supplier for Intel Purley server platform



No. 1 Taiwan CCL supplier for 5G base station



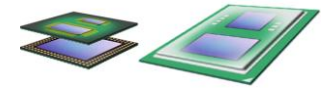
New product for HDI PCB: Resin Coated Copper (RCC)



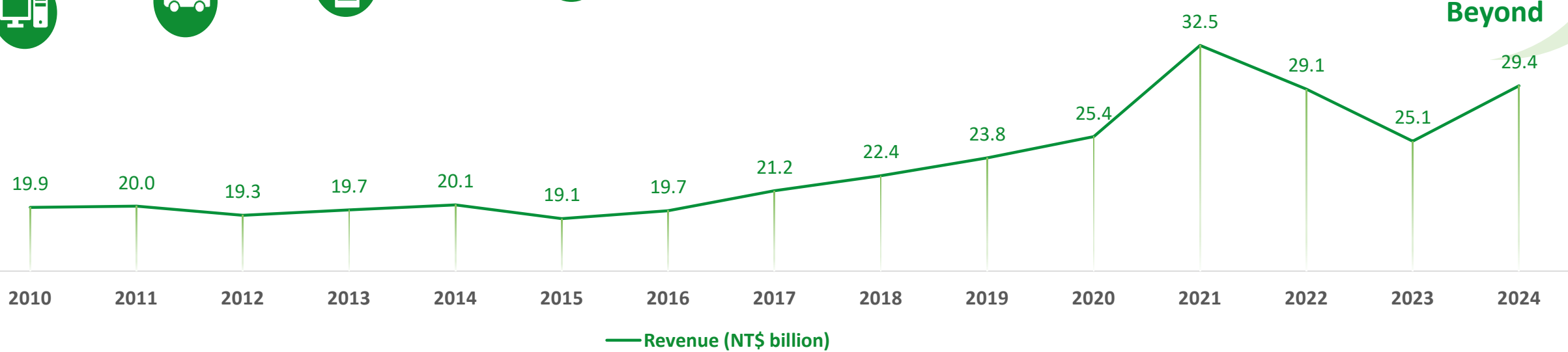
AI Applications CCL



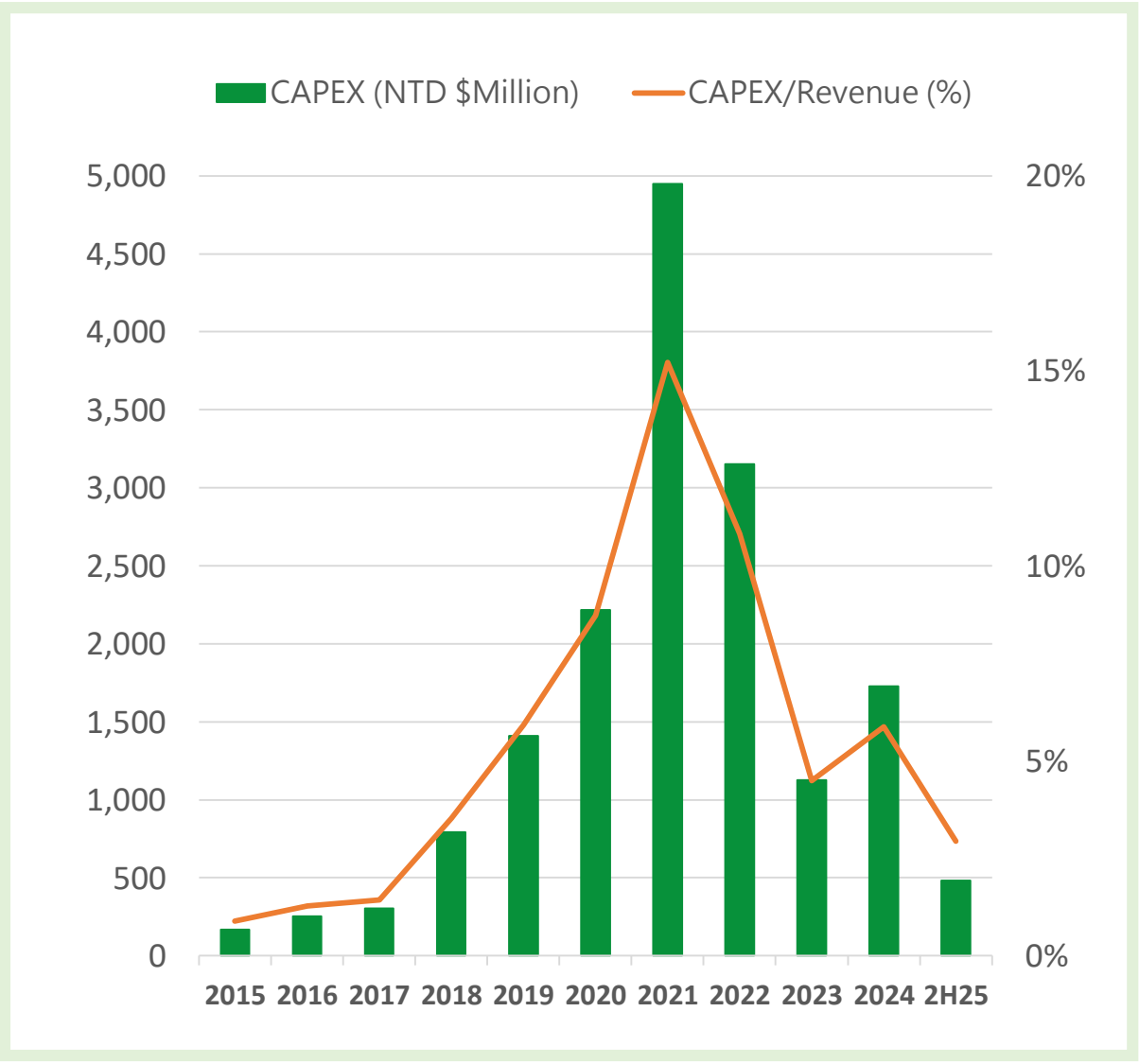
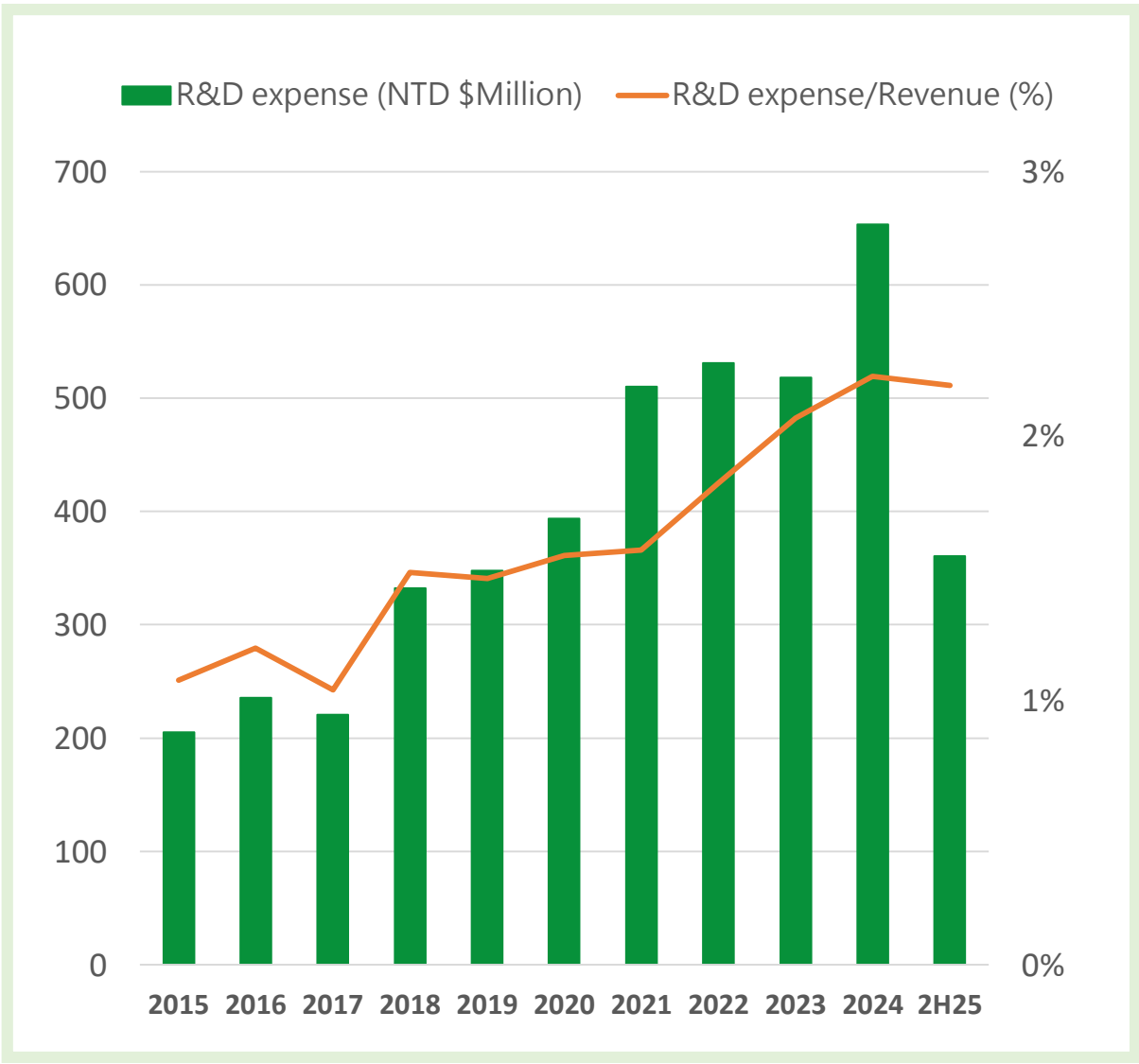
Substrate Like PCB (SLP) IC Packaging Substrate Laminate



Beyond

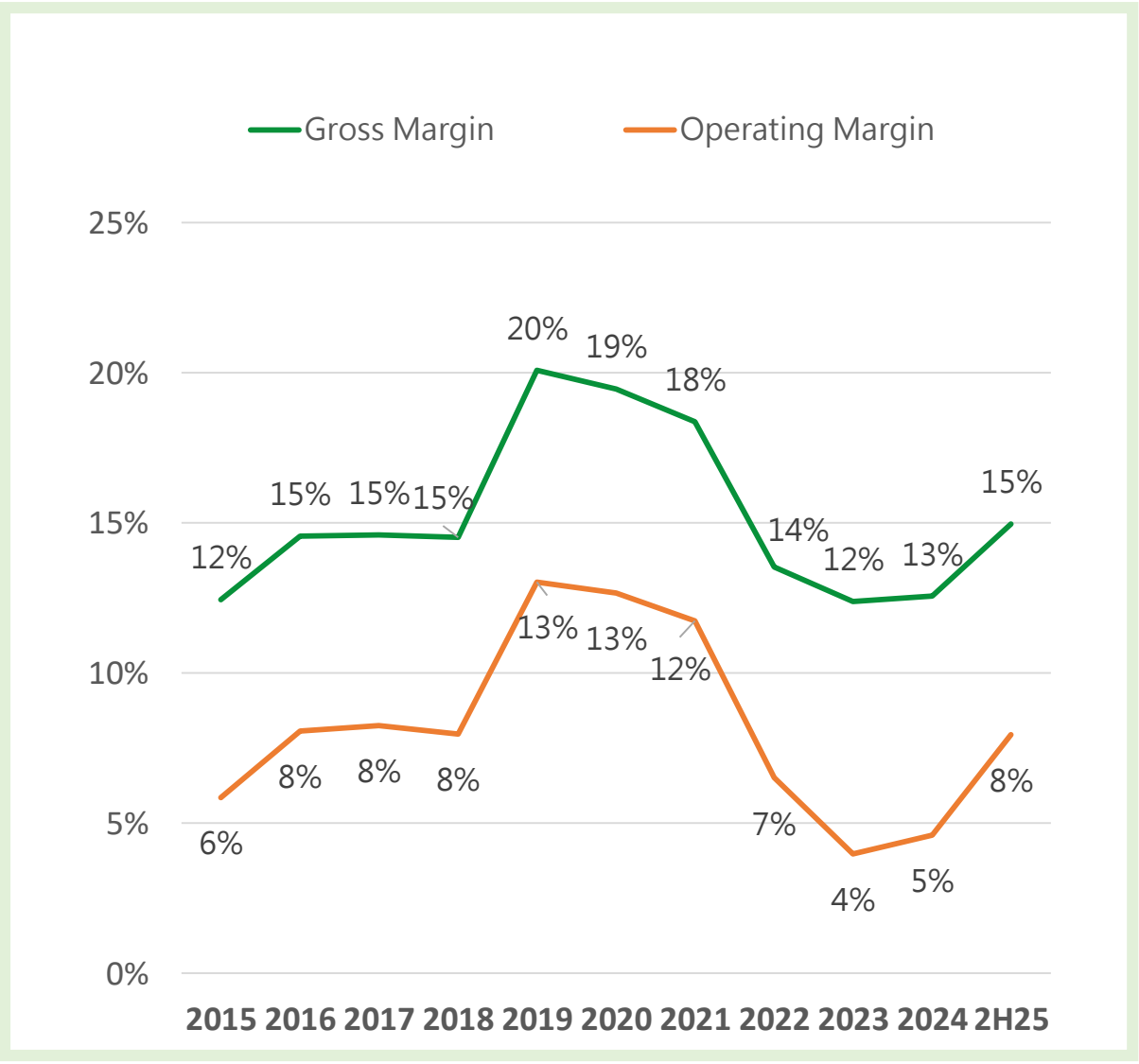
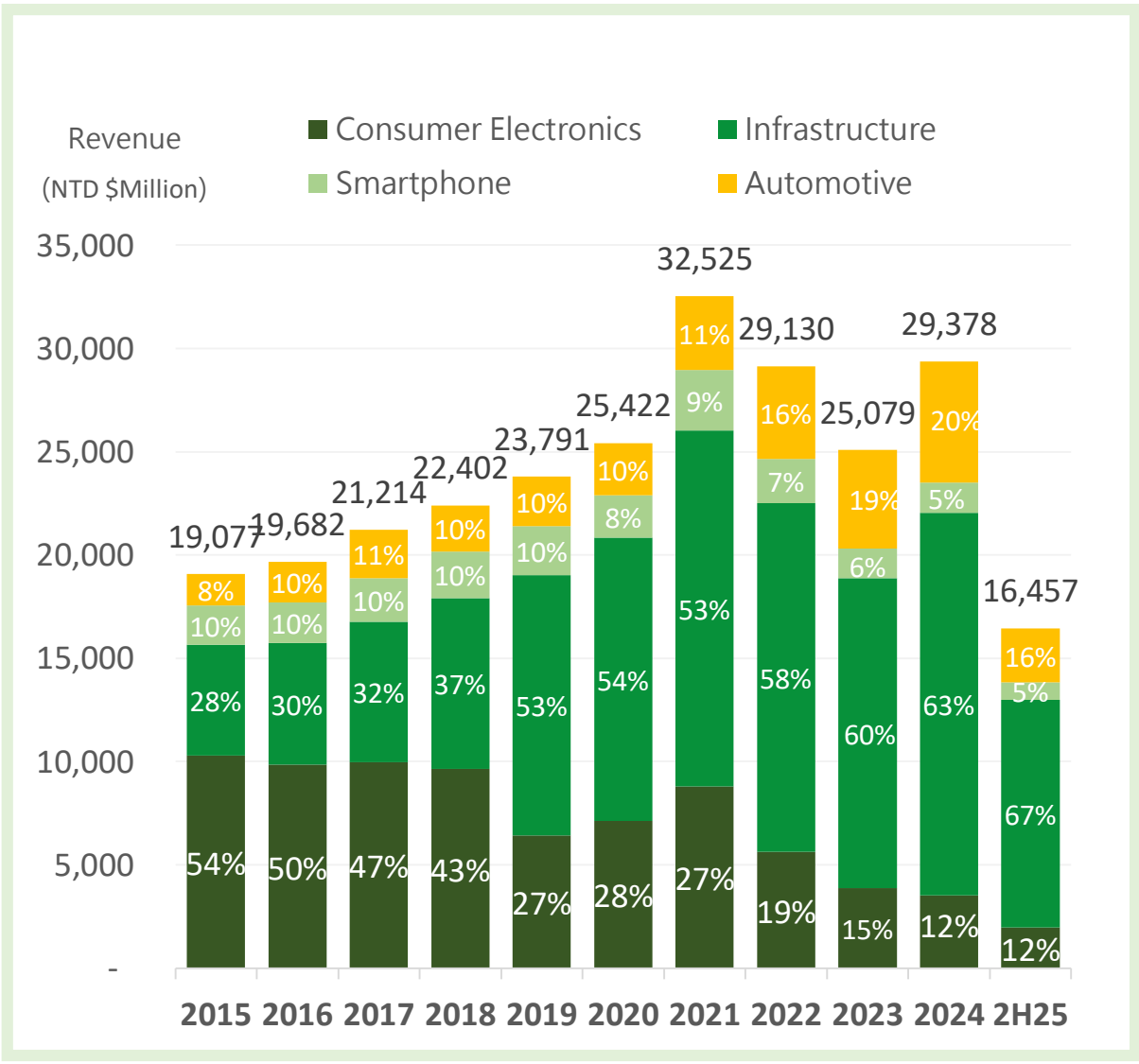


R&D and Capex to Pursuit Sustainable Growth



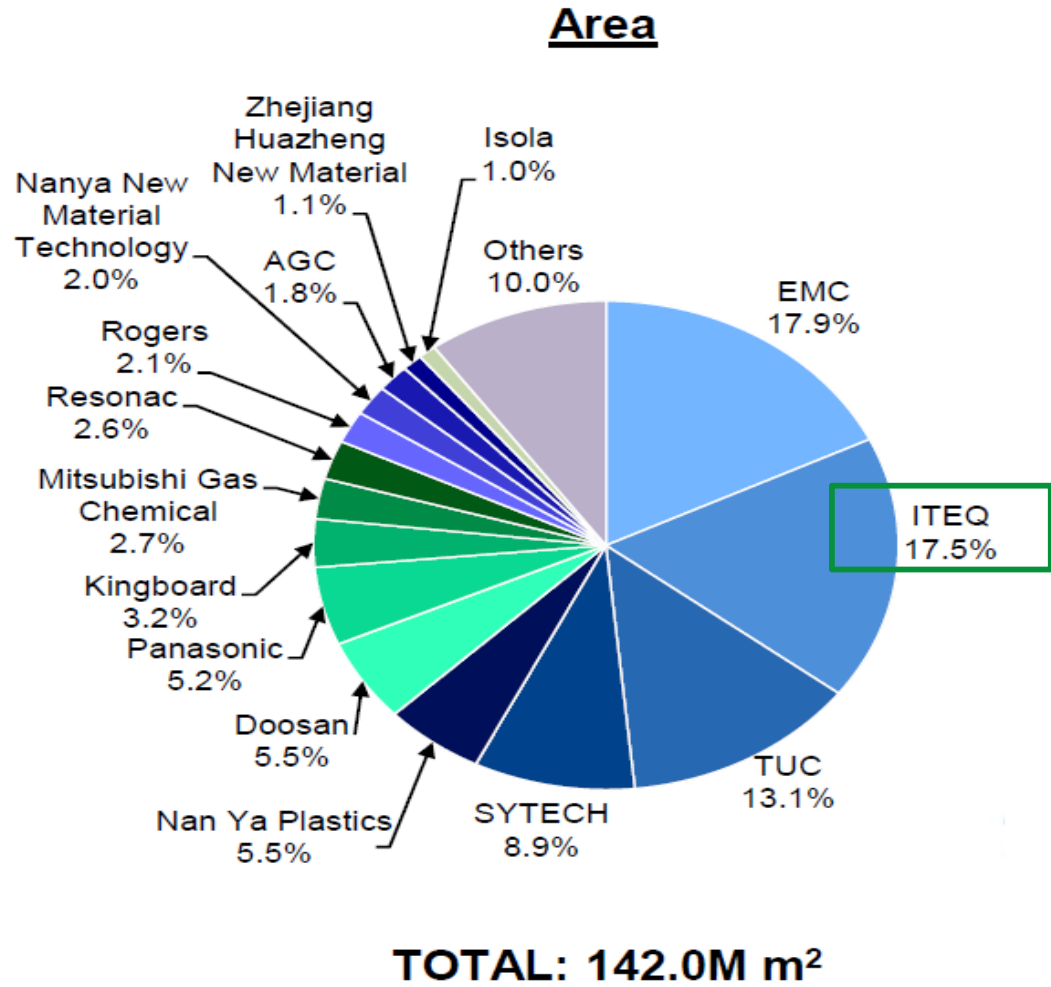
*2H25 CAPEX including the increase in prepayments for equipment NT\$320m.

Optimized Mix with Product Innovation



2024 WW Specialty Laminate Market Share

ITEQ: Leading CCL supplier



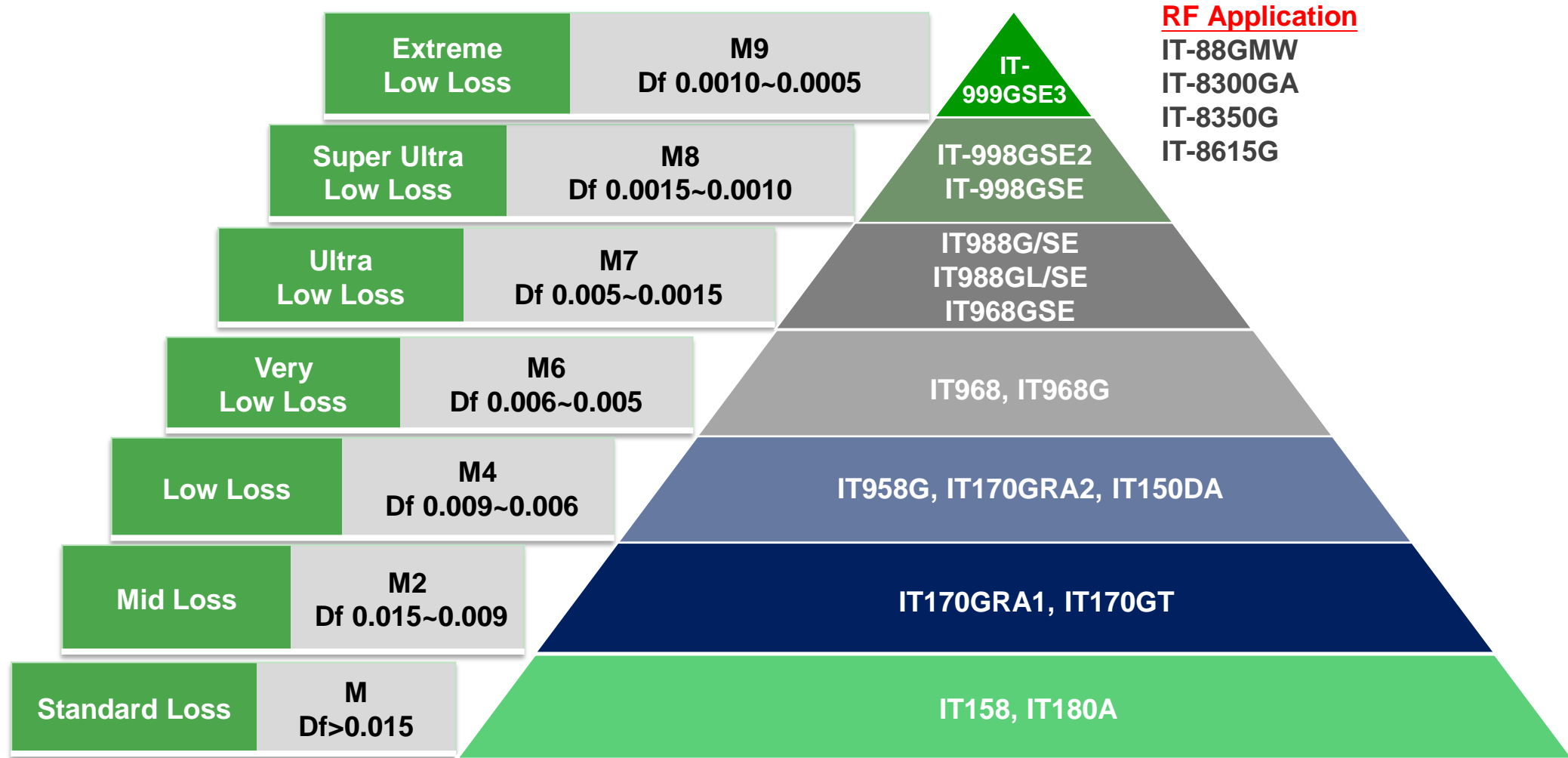
- Worldwide top supplier in high speed / frequency laminate
- Cutting-edge technology with MP track record
- Secular growth momentum in network infrastructure and data centers upgrading opportunities
- Megatrend automotive market to boost demand for high speed / frequency automotive CCL



INNOVATION · TEAMWORK · EXCELLENCE · QUALITY

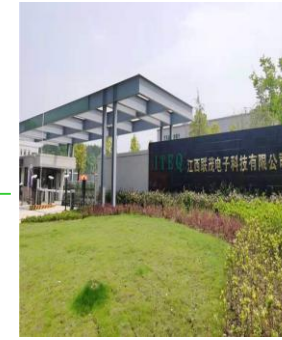
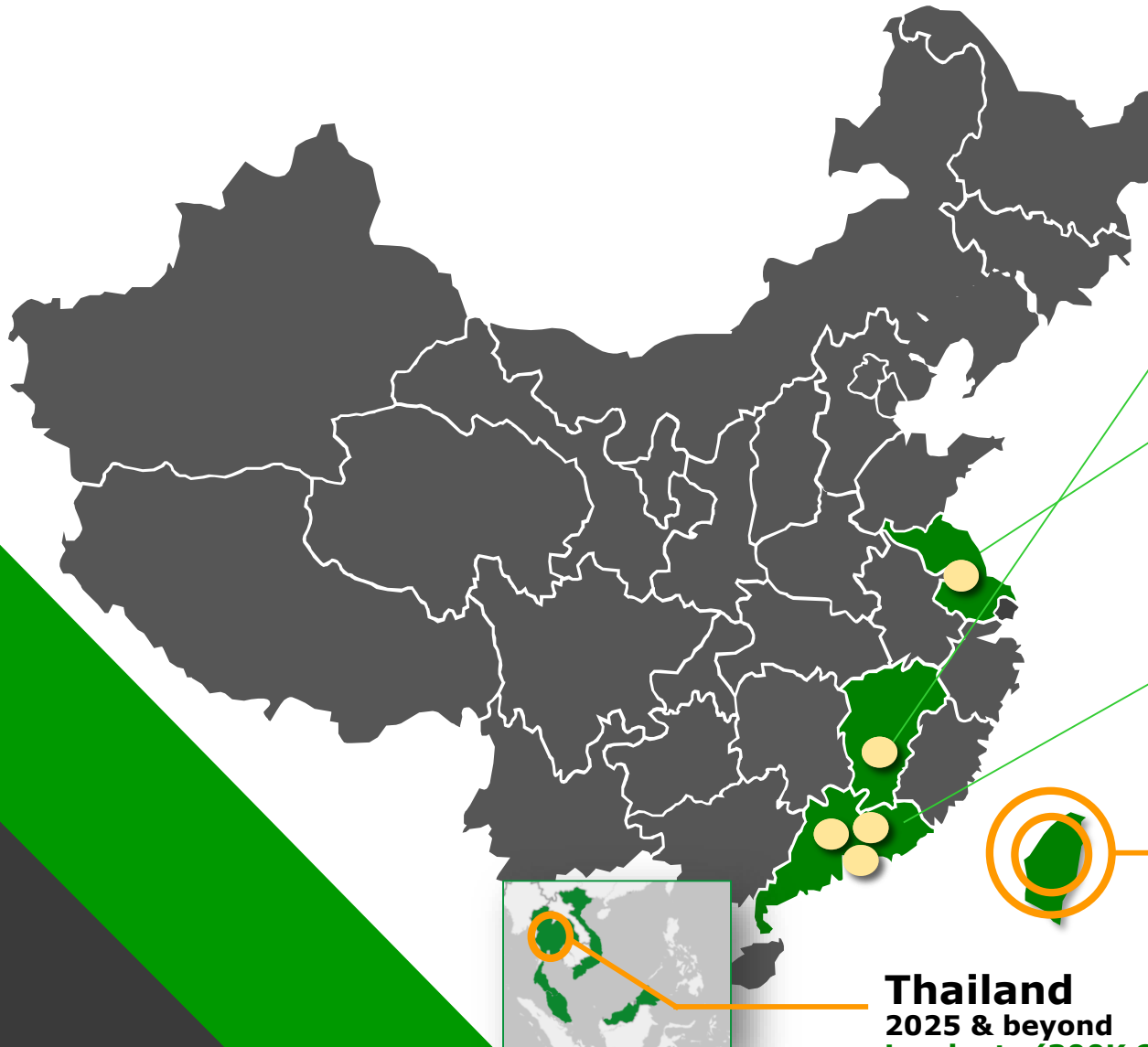
*Specialty Laminate includes: High speed, package substrate, RF
Source: Prismark Report, 2025/06

Well-Expanded Product Line



- The need for hyperscale data center and AI server upgrade to expedite the growth of high speed / frequency material demand
- ITEQ's market share in high speed / frequency material to uplift robustly

Manufacturing Site & Capacity – Expansion Plan ITEQ



JiangXi Plant
(Phase I) - 2020
Laminate (600K SHT/Month)
Prepreg (3,500K M/Month)
(Phase II) - 2021
Laminate (600K SHT/Month)
Prepreg (3,500K M/Month)
(Phase III) – 2022 & 2023
Laminate (1,200K SHT/Month)
Prepreg (5,000K M/Month)



WuXi Plant
Laminate (1,650K SHT/Month)
Prepreg (8,000K M/Month)



DongGuan Plant
Laminate (1,000K SHT/Month)
Prepreg (4,000K M/Month)



GuangZhou Plant
FCCL (1,450 K M²/Month)



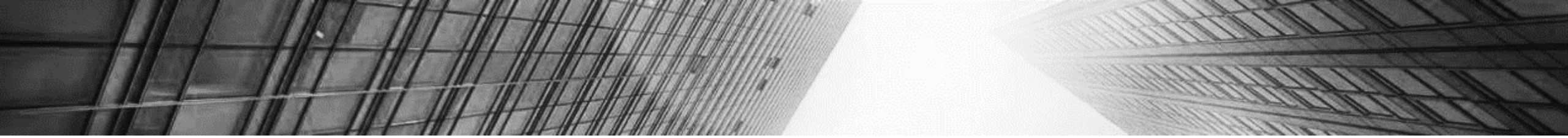
HuangJiang Plant
Masslam Service (500K SQFT/Month)



**HsinChu
(Headquarters)**
Laminate (400K SHT/Month)
Prepreg (2,400K M/Month)

Thailand
2025 & beyond
Laminate (300K SHT/Month)
Prepreg (TBD)

Distributor/Agent: USA, Europe, Israel, Korea, Japan and Singapore



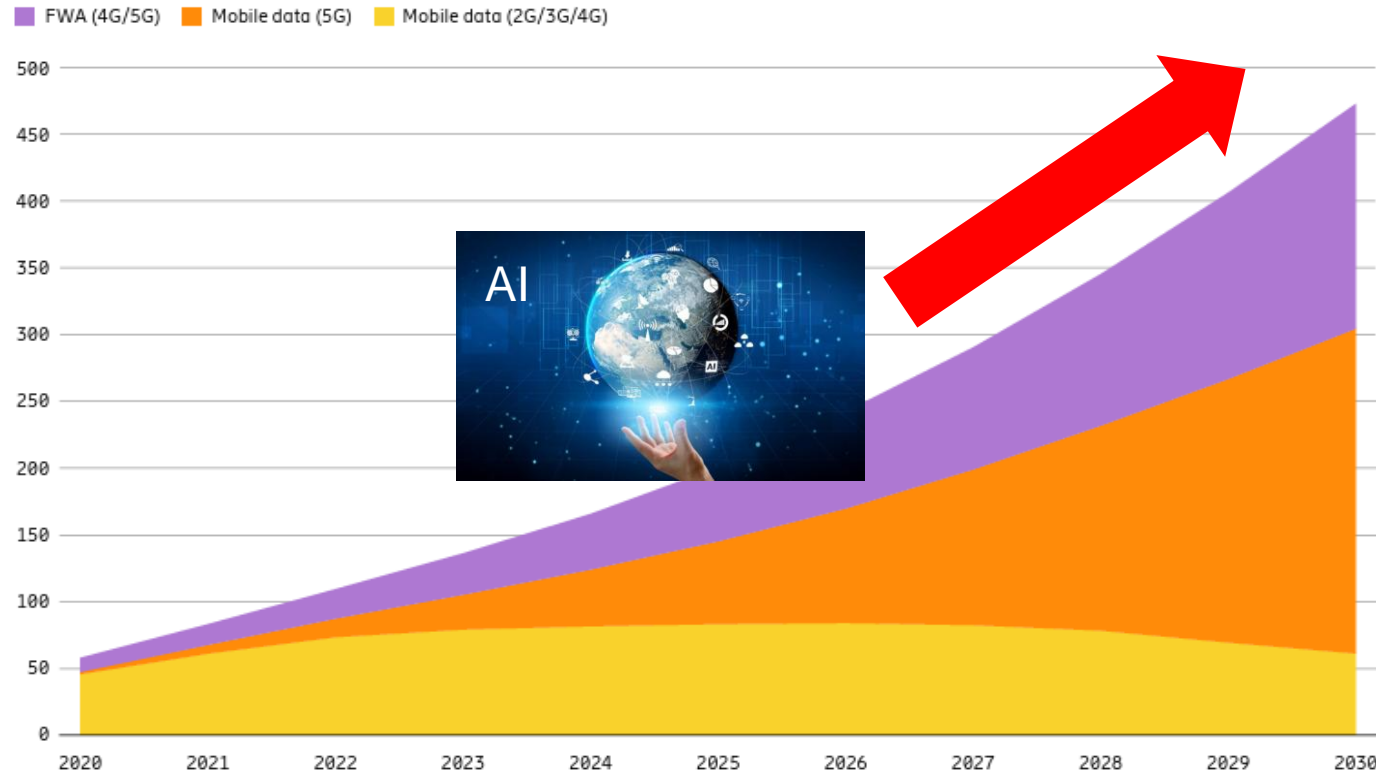
Market Trend & Growth Drivers

ITEQ

ITEQ

INNOVATION • TEAMWORK •
EXCELLENCE • QUALITY

Global Mobile Network Data Traffic (EB per month)



Source : Ericsson Mobility Report, 2024/11

● The Expansion of Global Mobile Network Data Traffic Continues on the Rise

- AI & High-Performance Computing & Big Data Analysis
 - Edge computing (Enterprise enhanced infrastructure, such as data center & internal/external servers, signal transmission stations, etc.)
- Telecommunications equipment & datacenter
 - Base station, ground satellite transceiver station
 - Core (traditional / cloud datacenter)
- Cloud Computing and Cloud Storage
- Internet of Vehicles (ADAS & Self-Driving)
- End user products (computers, smartphones, IoT devices)
- IoT related applications (Smart Home & Telemedicine)
- Virtual Reality (VR) and Augmented Reality (AR)

- The expansion of global mobile network data traffic has driven cloud service providers (CSP), telecom companies and IoT & IoV manufacturers to expand/upgrade product specs to meet the needs of low latency, high reliability and high-speed computing processing.
- Global Server shipment growth intact
 - Generative AI to drive demand for both AI servers and general-purpose servers
 - AI server robust demand to drive CCL content growth

Datacenter Server Platform Upgrade

Intel	Platform	Purley		Whitley	Eagle Stream		Birch Stream
	CPU	Skylake	Cascade Lake	Ice lake	Sapphire Rapids	Emerald Rapids	Granite Rapids
	Nano Process	14 nm	14 nm+	10 nm	Intel 7	Intel 7	Intel 3
	PCIe Gen	PCIe 3.0	PCIe 3.0	PCIe 4.0	PCIe 5.0	PCIe 5.0	PCIe 5.0
	MP Time	2017 Q3	2019 Q3	2021 Q1	2023 H1	2023 H2	2024
	CCL Material	Mid Loss	Mid Loss	Low Loss	Very Low Loss	Very Low Loss	VLL/ Ultra Low Loss
	Layer count	8 to 12	8 to 12	12 to 16	16 to 20	16 to 20	18 to 22



AMD	Architecture	Zen	Zen2	Zen3	Zen4		Zen5
	CPU	Naples	Rome	Milan	Genoa	Bergamo	Turin
	Nano Process	14 nm (Global Foundries)	7 nm (TSMC)	7 nm (TSMC)	5 nm (TSMC)	5 nm (TSMC)	4 nm / 3 nm (TSMC)
	PCIe Gen	PCIe 3.0	PCIe 4.0	PCIe 4.0	PCIe 5.0	PCIe 5.0	PCIe 5.0
	MP Time	2017 Q3	2019 Q3	2020 Q4	2022 Q4	2023	2024
	CCL Material	Mid Loss	Low Loss	Low Loss	Very Low Loss	Very Low Loss	VLL/ Ultra Low Loss
	Layer count	8 to 12	12 to 16	12 to 16	16 to 20	16 to 20	18 to 22

Datacenter Equipment Cyclical Upgrade to Drive the Following;

- Corresponding CCL material upgrade
- Increase consumption and layer counts for CCL

Green Power/EV



- Energy Conservation
- Power Charging
- High Current & Voltage
- Heavy Cu

High Tg material

Internet of Vehicle

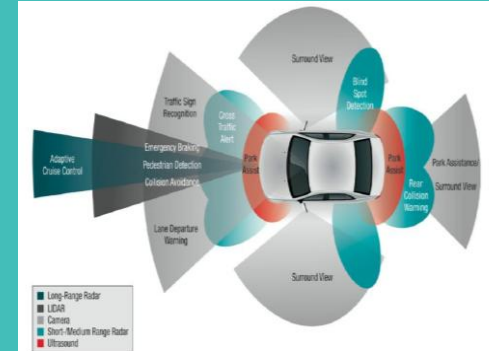


- Infotainment
- Networking

HDI

High Speed Material

Active Safety



- Active Safety System
- ADAS
- Radar
- Antenna Module

HDI

High Speed Material

High Frequency Material

Autonomous Driving

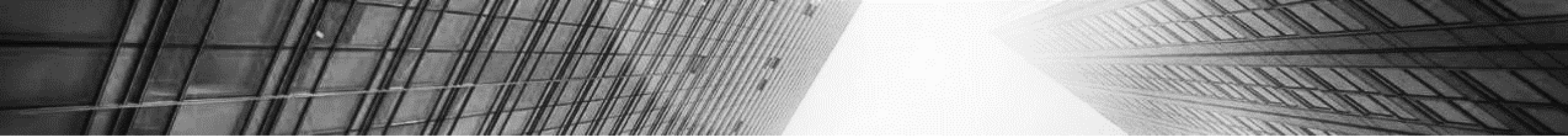


- HPC
- Graphic Processing
- Automated Driving Control Module

HDI

High Speed Material

- EV, IoV and Active Safety to boost demand for high performance automotive CCL
- PCB usage for EV is 4 to 5 folds of conventional gasoline vehicle



2Q25 Financial Results

ITEQ

ITEQ

INNOVATION • TEAMWORK •
EXCELLENCE • QUALITY

2Q25 Income Statement

NTD \$Million

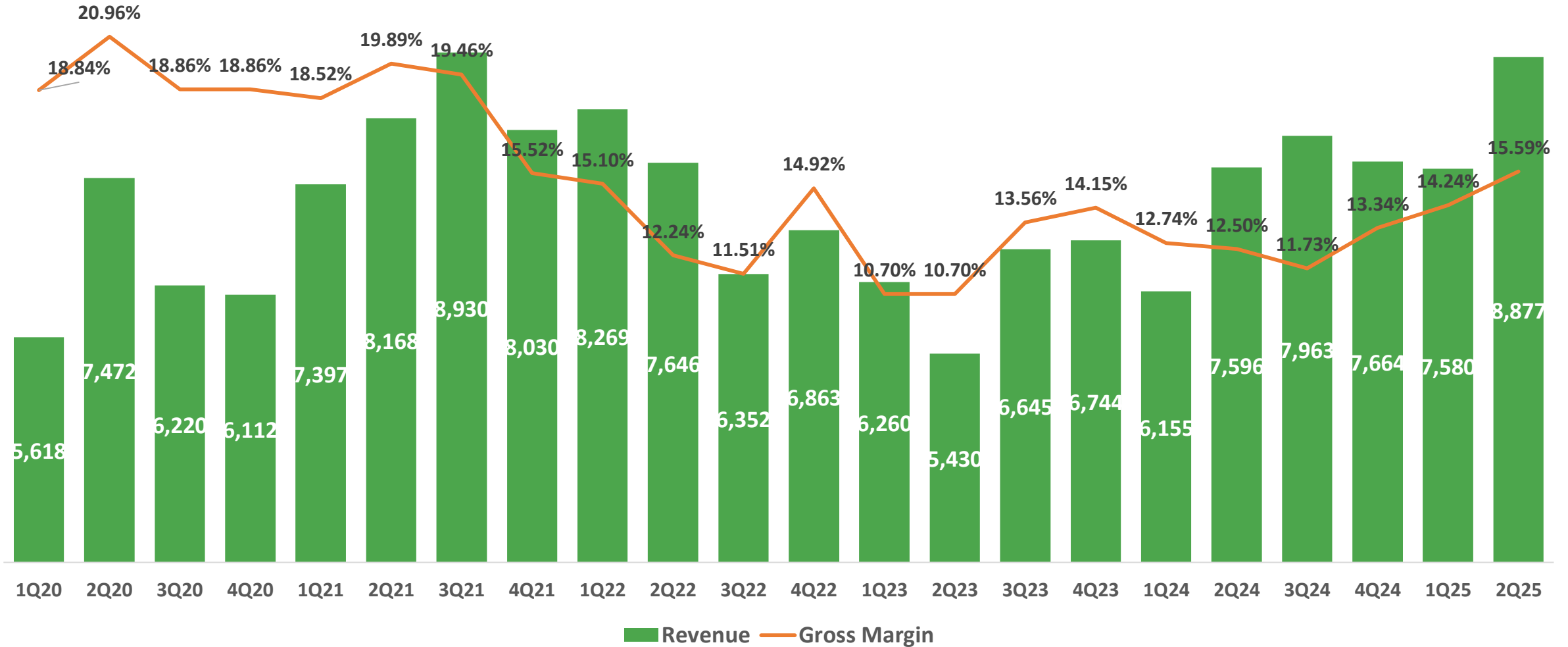
	2Q25	1Q25	2Q24	QoQ	YoY
Revenue	8,877	7,580	7,596	17.1%	16.9%
Gross Profit	1,384	1,080	949	28.1%	45.8%
Operating Expense	596	558	611	6.8%	-2.5%
Operating Profit	788	521	338	51.2%	133.1%
Non-Op Income / Loss	(118)	13	(12)		
Income before Tax	670	535	326	25.2%	105.5%
Tax Expense	250	198	126		
Net Income to Parent	420	337	200	24.6%	110.0%
EPS(NT\$)	1.16	0.93	0.55	24.7%	110.9%
Key Financial Ratio					
Gross Margin	15.59%	14.25%	12.49%		
Operating Expense Ratio	6.71%	7.36%	8.04%		
Operating Margin	8.88%	6.87%	4.45%		
Effective Tax Rate	37.31%	37.01%	38.65%		
Net Margin	4.73%	4.45%	2.63%		

2Q25 Balance Sheet

NTD \$Million	2Q25	1Q25	2Q24
Total Assets	34,940	36,256	37,278
Cash	3,348	4,791	5,139
NR / AR	13,537	12,561	13,282
Inventories	4,285	4,047	4,537
Fixed Assets	8,858	9,952	9,135
Total Liabilities	16,552	15,588	16,984
Short-term Debt	4,038	4,003	3,207
AP	8,000	6,995	8,003
Long-term Debt	1,496	1,581	2,679
Total Equity	18,387	20,669	20,295
Key Financial Index			
Days Sales Outstanding	150	150	167
Days Sales of Inventory	58	59	65
Days Payable Outstanding	94	90	108
ROE (%)	6.3	4.9	4.6
ROA (%)	3.9	3.2	2.8
Debt ratio (%)	47.4	43.0	45.6

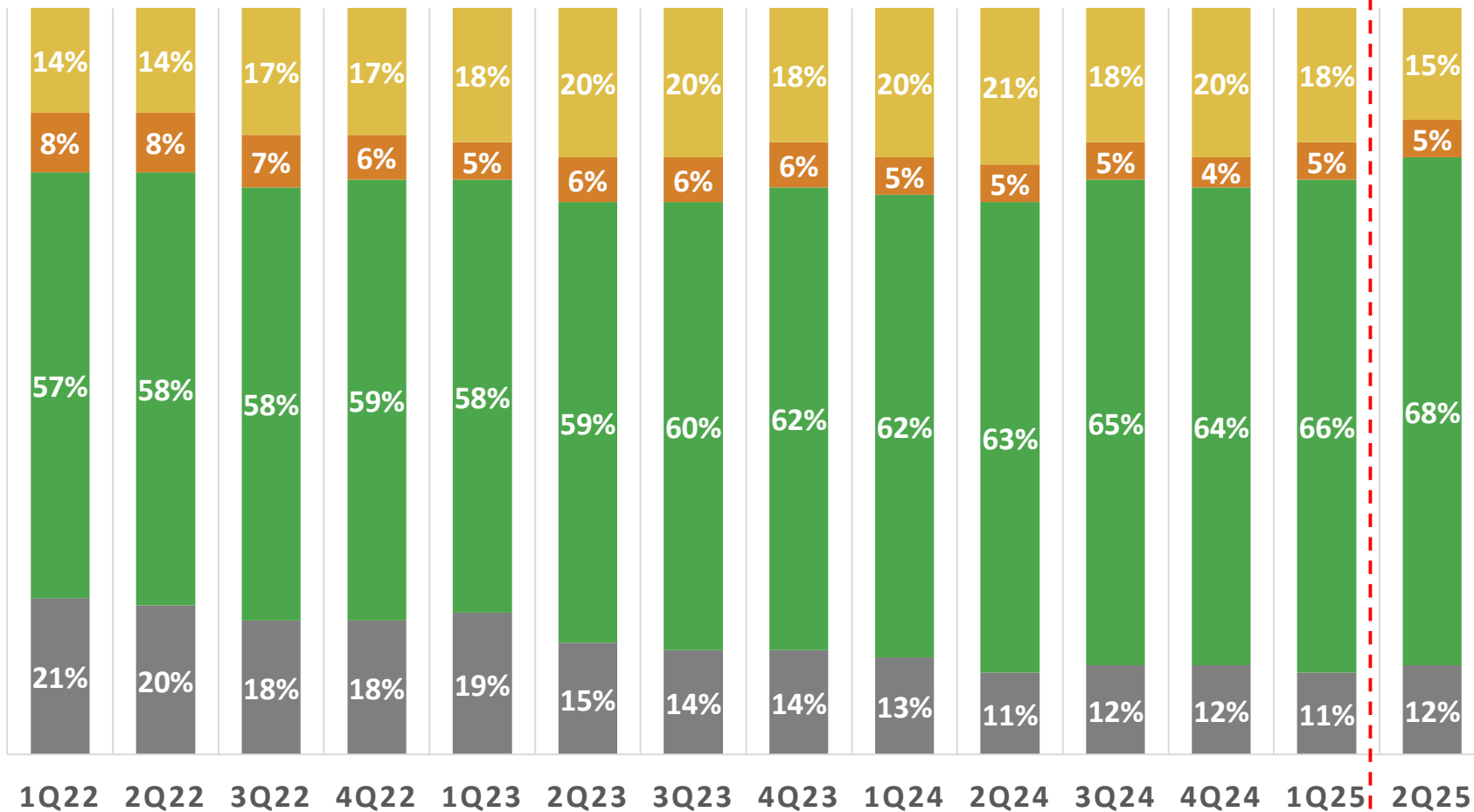
Revenue & Gross Margin Rate

(Million \$NTD)



Product Mix

■ Consumer Electronics ■ Infrastructure ■ Smartphone ■ Automotive



2Q25 Product Growth	QoQ	YoY
Automotive	-2.4%	-16.5%
Smartphone	+17.1%	+16.9%
Infrastructure	+20.7%	+26.1%
Consumer Electronics	+27.8%	+27.5%

Year	EPS(NT\$)	Dividend(NT\$)	Cash Dividend(NT\$)	Pay-out Ratio(%)
2018	5.86	3.8	3.8	65%
2019	8.13	5.0	5.0	62%
2020	8.19	5.0	5.0	61%
2021	9.00	5.0	5.0	56%
2022	4.94	3.0	3.0	61%
2023	1.86	1.5	1.5	81%
2024	2.26	1.8	1.8	80%

*New shares issuance of 30 million common shares concluded on March 31st 2020

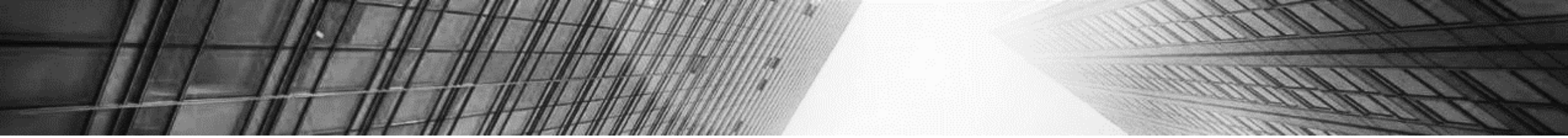
**New shares issuance of 50 million common shares concluded on September 2nd 2021

***Factoring in the repurchase and cancellation of 20 million shares in 3Q22; current total outstanding common share: 363 million



Thank you

Question and Comment



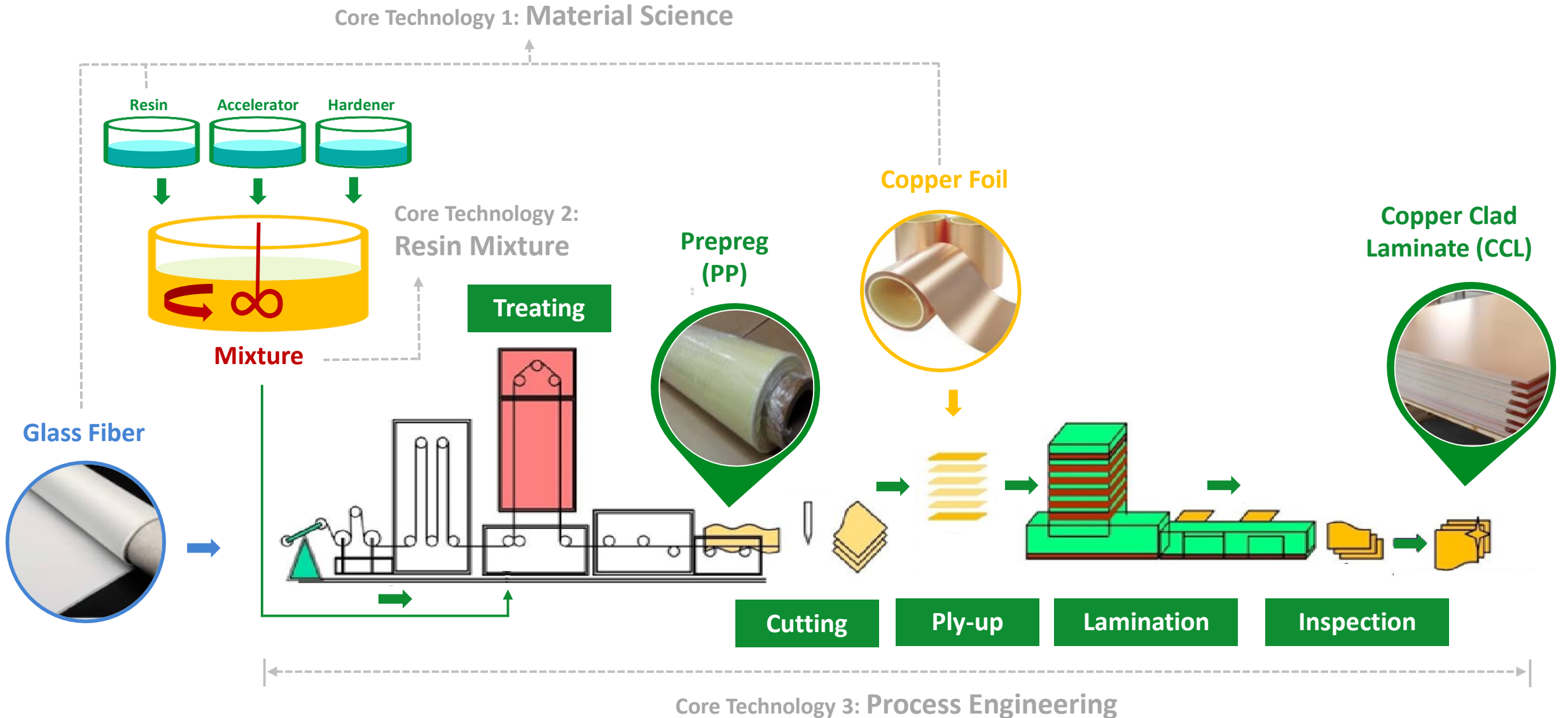
Appendix

ITEQ

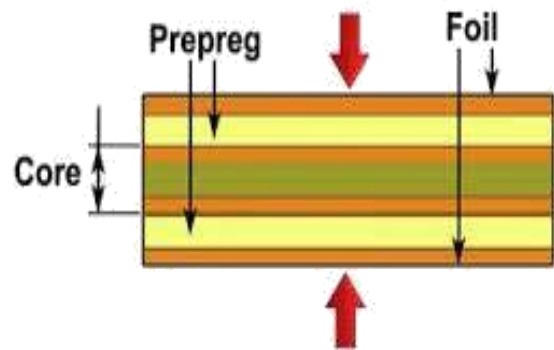
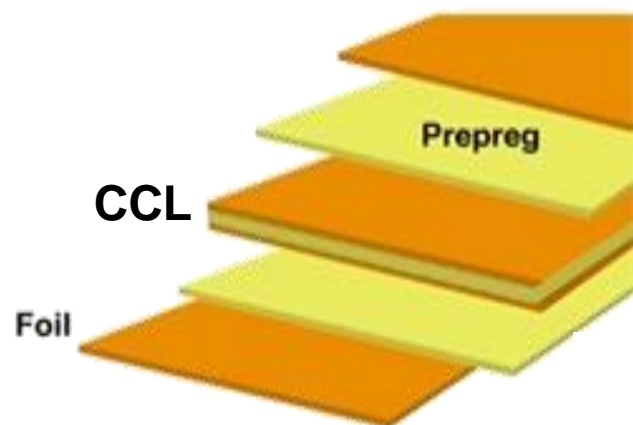
ITEQ

INNOVATION • TEAMWORK •
EXCELLENCE • QUALITY

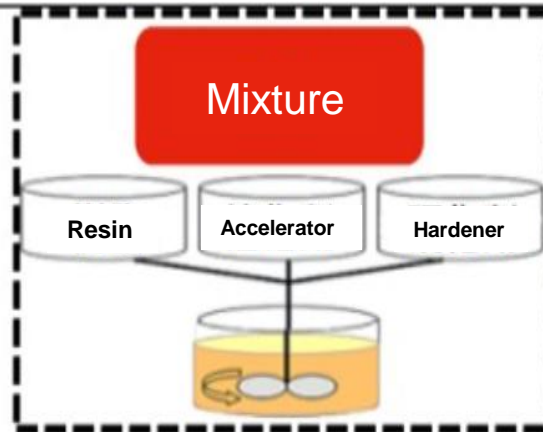
CCL & PP Manufacturing Flow



CCL/PP



CCL Manufacturing Process



Glass Fiber



CCL



Copper Foil



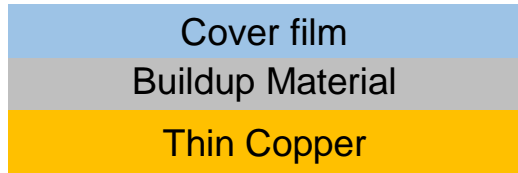
PP



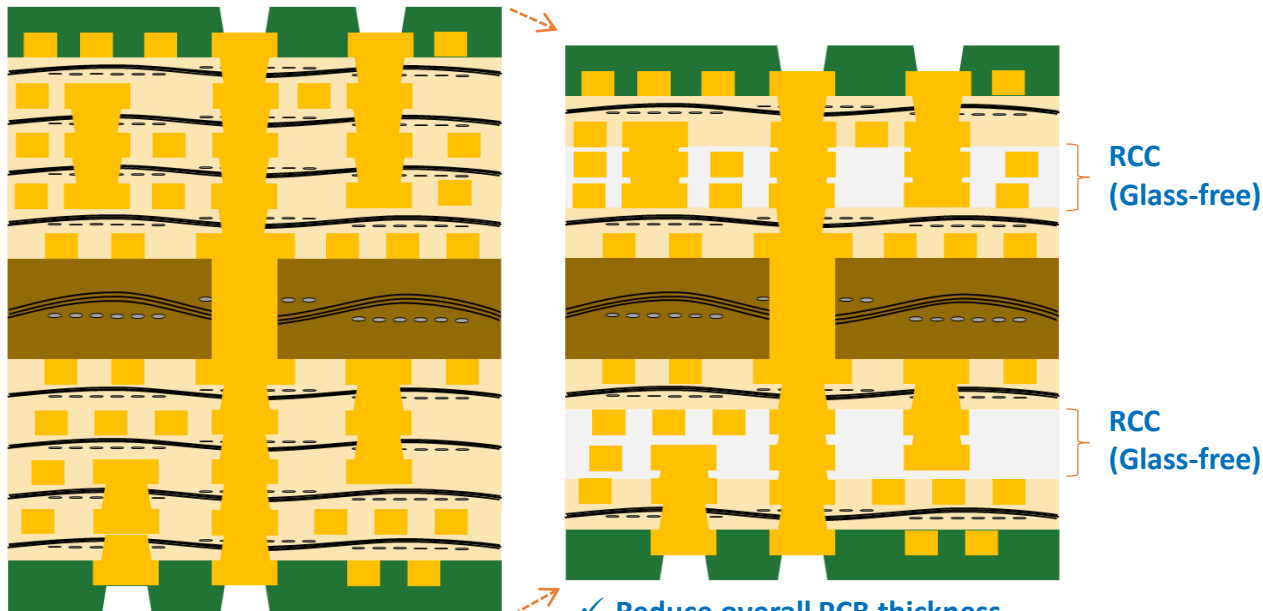
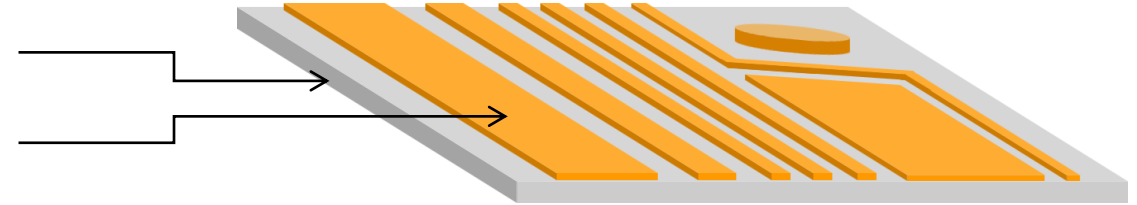
HDI New Product: Resin Coated Copper (RCC)

Resin Coated Copper (RCC)

- ✓ Glass-free solution which enables further thickness reduction of dielectric layer while satisfies the needs towards fine-line pattern design (smaller form factor) and hybrid HDI/Substrate-Like PCB production.



Dielectric Layer : 10~50um
※ Available for thickness up to 150um
Conductors : Copper Foil



- ✓ Reduce overall PCB thickness
- ✓ Eliminate the fiber weave effect with enhanced reliability of signal transmission

ITEQ RCC Advantages

Glass-Free

Reduce thickness of the dielectric layer and overcome minimum thickness constraints (15-20um)

Better Dielectric Constant (Dk) and Impedance Control

RCC uses pure glue material enabling stable dielectric constant

Power Consumption Saving

Lower voltage – extending battery life

Better Laser Processability

RCC is a glass fiber free material, which is easier to form holes through laser drilling with more stable Via quality

Simplify PCB Lamination process

Combine the processes of PP/Copper foil stack-up into one

AI Server CPU*2 Mainboard (Content Value – mid)

(Used in both general type server and AI server)
CPU MB

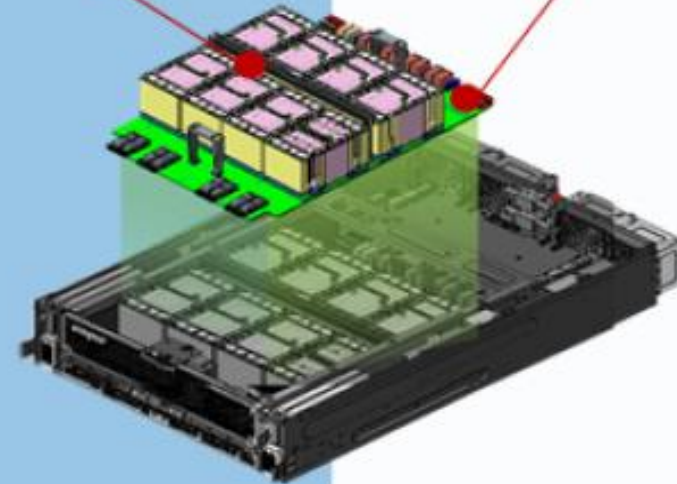


CCL: Very Low Loss
Layer Count: 14 to 24

AI Server GPU OAM*8 (Content Value – high)

(Used in accelerator card– AI server only)

GPU Tray



CCL: Very Low Loss
Layer count: 20 to 30 (HDI)

AI Server GPU UBB (Content Value – high)

(Used as GPU board– AI server only)

CCL: Ultra Low Loss / VLL
Layer count: 20 to 30 (incl. HDI)